

**Amendments to the claims**

1. (Currently amended) A method of forming a laminated composite printed wiring structure of a plurality of at least three superimposed subcomposites comprising the steps of:

providing a plurality of at least three organic dielectric subcomposite structures, each having a plurality of through via openings therein extending between said faces, and wherein the via openings in each subcomposite structure are positioned to align with a via opening in at least one subcomposite structure that is to be adjacent said each subcomposite structure, and printed wiring on at least one face of one subcomposite structure,

filling each via opening with a conductive paste material that can be hardened or cured with said conductive paste material extending beyond at least one face of the subcomposite structure,

providing a plurality of aligned index openings in each subcomposite structure which will cooperate with a fixture to align at least some of said via holes in adjacent subcomponent structures when in superimposed relationship,

providing adhesive in the form of separate adhesive sheets for location between adjacent superimposed structures, said adhesive sheets having openings for said conductive paste,

laying up said subcomposite with said adhesive material disposed there between in superimposed relationship on a fixture, including elements extending through said index openings to align said subcomposite structures with conductive paste in adjacent via openings in said subcomposite structures, in contact with each other; and

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fully curing said conductive paste in said adjacent superimposed structures to form a laminated composite structure.

2. (Canceled)

3. (Original) The invention as defined in claim 1 wherein said via openings have plated conductive surfaces.

4. (Original) The invention as defined in claim 1 wherein said via openings are free of plating therein.

5. (Previously presented) The invention as defined in claim 1 wherein at least some of said via openings are copper plated.

6. (Original) The invention as defined in claim 1 wherein said conductive paste is partially cured or dried before the subcomposites are laminated.

7. (Previously presented) The invention as defined in claim 1 wherein said via openings are filled with said conductive paste through a mask.

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8. (Previously presented) The invention as defined in claim 7 wherein each of said subcomposites are registered with said registration openings and said mask to fill the via openings with the conductive paste.

9. (Original) The invention as defined in claim 7 wherein circuitry is applied to at least one side of at least one of said subcomposite through said mask.

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